

EMF700

SERVICE MANUAL



EMP700

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IMPORTANT NOTICE

This manual has been provided for the use of authorized Yamaha Retailers and their service personnel. It has been assumed that basic service procedures inherent to the industry, and more specifically Yamaha Products, are already known and understood by the users, and have therefore not been restated.

WARNING: Failure to follow appropriate service and safety procedures when servicing this product may result in personal injury, destruction of expensive components and failure of the product to perform as specified. For these reasons, we advise all Yamaha product owners that all service required should be performed by an authorized Yamaha Retailer or the appointed service representative.

IMPORTANT: The presentation or sale of this manual to any individual or firm does not constitute authorization, certification, recognition of any applicable technical capabilities, or establish a principle-agent relationship of any form.

The data provided is believed to be accurate and applicable to the unit(s) indicated on the cover. The research, engineering, and service departments of Yamaha are continually striving to improve Yamaha products. Modifications are, therefore, inevitable and changes in specification are subject to change without notice or obligation to retrofit. Should any discrepancy appear to exist, please contact the distributor's Service Division.

WARNING: Static discharges can destroy expensive components. Discharge any static electricity your body may have accumulated by grounding yourself to the ground buss in the unit (heavy gauge black wires connect to this buss).

IMPORTANT: Turn the unit OFF during disassembly and parts replacement. Recheck all work before you apply power to the unit.

This product uses a lithium battery for memory back-up.

WARNING: Lithium batteries are dangerous because they can be exploded by improper handling. Observe the following precautions when handling or replacing lithium batteries.

- Leave lithium battery replacement to qualified service personnel.
- Always replace with batteries of the same type.
- When installing on the PC board, solder using the connection terminals provided on the battery cells. Never solder directly to the cells. Perform the soldering as quickly as possible.
- Never reverse the battery polarities when installing.
- Do not short the batteries.
- Do not attempt to recharge these batteries.
- Do not disassemble the batteries.
- Never heat batteries or throw them into fire.

ADVARSEL!

Lithiumbatteri. Eksplosionsfare.

Udskiftning må kun foretages af en sagkyndig, og som beskrevet i servicemanualen.

WARNING: CHEMICAL CONTENT NOTICE!

The solder used in the production of this product contains LEAD. In addition, other electrical/electronic and/or plastic (where applicable) components may also contain traces of chemicals found by the California Health and Welfare Agency (and possibly other entities) to cause cancer and/or birth defects or other reproductive harm.

DO NOT PLACE SOLDER, ELECTRICAL/ELECTRONIC OR PLASTIC COMPONENTS IN YOUR MOUTH FOR ANY REASON WHAT SO EVER!

Avoid prolonged, unprotected contact between solder and your skin! When soldering, do not inhale solder fumes or expose eyes to solder/flux vapor!

If you come in contact with solder or components located inside the enclosure of this product, wash your hands before handling food.

■ SPECIFICATIONS

• Inputs	2 channels, 1/4" phone jack, impedance greater than 500K Ω .
• Outputs	2 channels, 1/4" phone jack, impedance 1K Ω .
• Input/Output Level	-20dB/+4dB switchable.
• Sampling Frequency	44.1 kHz.
• Quantization	16 bits.
• Frequency Response	20 Hz ... 20 kHz.
• Dynamic Range	Greater than 85 dB, effect off.
• T.H.D	Less than 0.1% @ 1 kHz.
• Internal Memory	90 presets in ROM, 50 user RAM.
• External Memory	RAM (50 programs) cards, optional.
• Power Consumption	US & Canadian model: 120V AC, 10 watts. General model: 220 ... 240V AC, 10 watts.
• Dimensions (W x H x D)	480 x 44 x 216.2 mm. (18-7/8" x 1-3/4" x 8-1/2")
• Weight	2.9 kg. (6 lbs. 6 oz)

■ 総合仕様

電気特性

周波数特性	20Hz~20 kHz
ダイナミックレンジ	85dB (@エフェクトOFF時)
歪率	0.03% (@ 1 kHz)

インプット (INPUT)

チャンネル数	2 cH
入力レベル	+ 4 dBm / - 20dBm
入力インピーダンス	500 k Ω 以上

アウトプット (OUTPUT)

チャンネル数	2 cH
出力レベル	+ 4 dBm / - 20dBm
出力インピーダンス	1 k Ω

AD/DA変換

チャンネル数	2 cH
サンプリング周波数	44.1 kHz
量子化ビット数	16bit

メモリー

プリセットプログラムエリア	No. 0 ~ 90 (No. 0 はイニシャルデータ)
ユーザーズプログラムエリア	No. 1 ~ 50
別売メモリーカードプログラムエリア	No. 1 ~ 50

MIDIコントロール

プログラムチェンジ、ノートオン、コントロールチェンジ、バルクダンプ機能	
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フロントパネル

スイッチ	POWER
コントロール	INPUT LEVEL (L, R)
キー	ソフトキー (▲)、アップダウンキー (▲, ▼)、MEMORY、PARAM (DYN, REV)、UTILITY、RECALL、STORE、ASSIGN、BYPASS

ディスプレイ

16文字×2行LCD(LED照明付き)
2桁7セグメントLED (メモリーナンバー)
2 cH、2 素子LED (レベルメーター)
3 素子LED (PRESET、USER、CARD表示)
1 素子LED (MIDI表示)
6 素子LED (モード表示)
メモリーカード

スロット

リアパネル

端子	INPUT L/R (フォーンジャック×2) OUTPUT L/R (フォーンジャック×2) MIDI IN, THRU/OUT (DIN 5 pin×2) TAP TEMPO/BYPASS (フォーンジャック)
スイッチ	入出力レベル切換スイッチ (+ 4 dB / - 20dB) MIDI THRU/OUT切換スイッチ

電源	AC100V、50/60Hz
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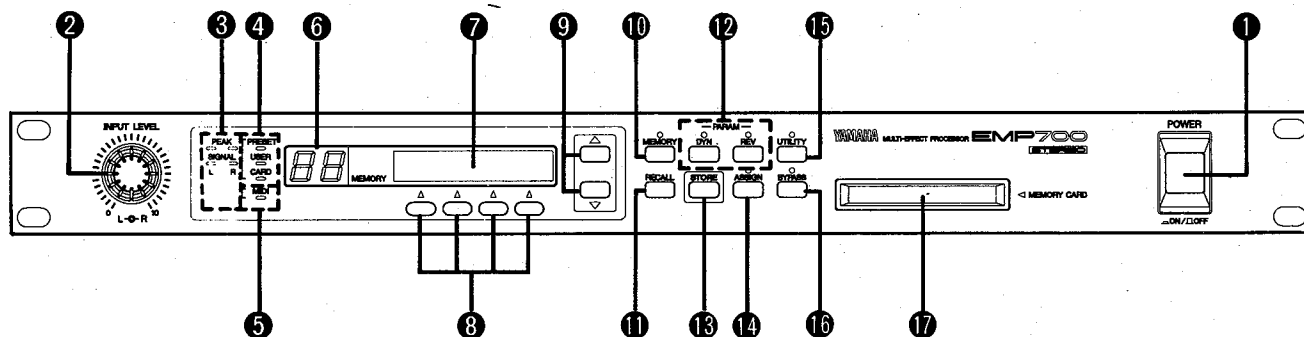
消費電力	8.5W
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寸法	480(W)×44(H)×216.2(D) mm
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重量	2.9kg
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■ PANEL LAYOUT (パネルレイアウト)

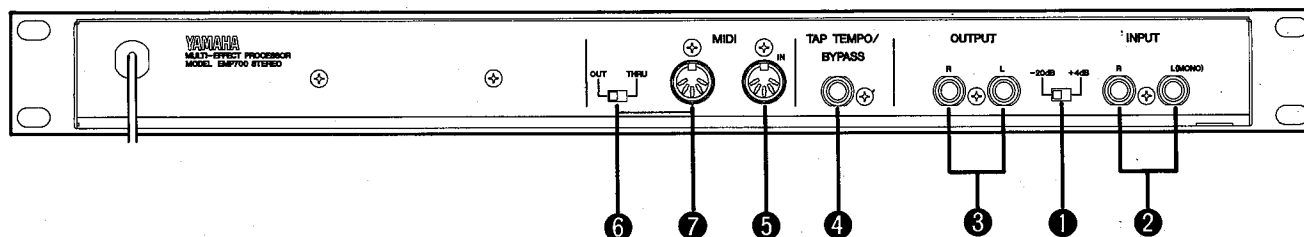
● Front Panel (フロントパネル)



- ① Power Switch
- ② INPUT LEVEL Controls
- ③ SIGNAL and PEAK Indicators
- ④ PRESET, USER and CARD Indicators
- ⑤ MIDI Indicators
- ⑥ LED MEMORY Number Display
- ⑦ Liquid Crystal Display
- ⑧ Assignable Function Keys
- ⑨ [▲] and [▼] Keys
- ⑩ [MEMORY] Mode Keys & Indicator
- ⑪ [RECALL] Key
- ⑫ PARAM Keys & Indicators (DYN, REV)
- ⑬ [STORE] Key
- ⑭ [ASSIGN] Key & Indicator
- ⑮ [UTILITY] Mode Key & Indicator
- ⑯ [BYPASS] Key & Indicator
- ⑰ MEMORY CARD Slot

- ① POWERスイッチ
- ② INPUT LEVELコントロール
- ③ SIGNAL, PEAKインジケーター
- ④ メモリーエリアインジケーター (PRESET, USER, CARD)
- ⑤ MIDIインジケーター
- ⑥ メモリーNo.ディスプレイ
- ⑦ LCDディスプレイ
- ⑧ ソフトキー
- ⑨ アップダウンキー
- ⑩ メモリー選択キーとインジケーター
- ⑪ メモリーRECALLキー
- ⑫ パラメーターエディットキー (DYN, REV)
- ⑬ メモリーSTOREキー
- ⑭ ASSIGNキーとインジケーター
- ⑮ UTILITYキーとインジケーター
- ⑯ BYPASSキーとインジケーター
- ⑰ メモリーカードスロット

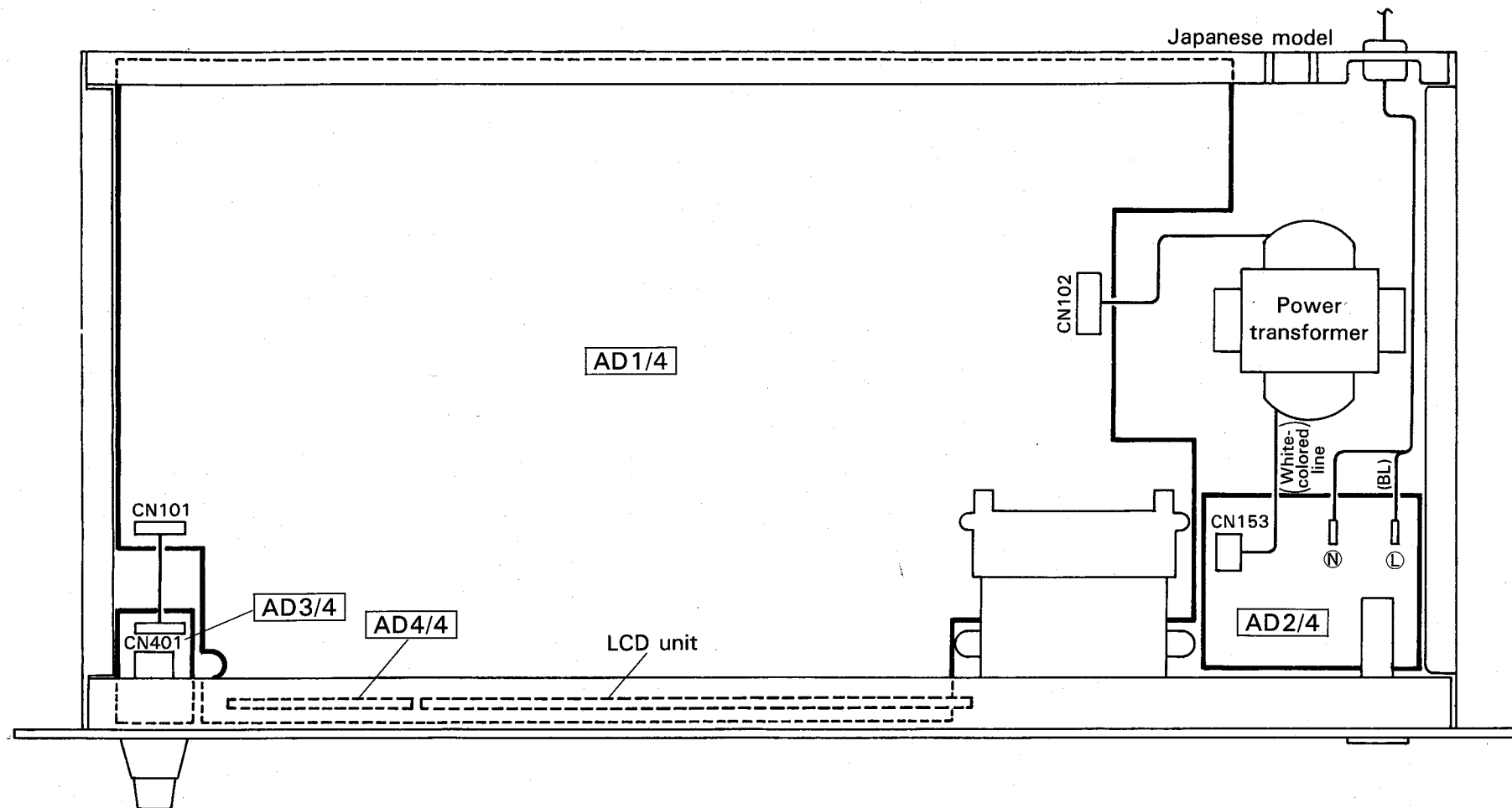
● Rear Panel (リアパネル)



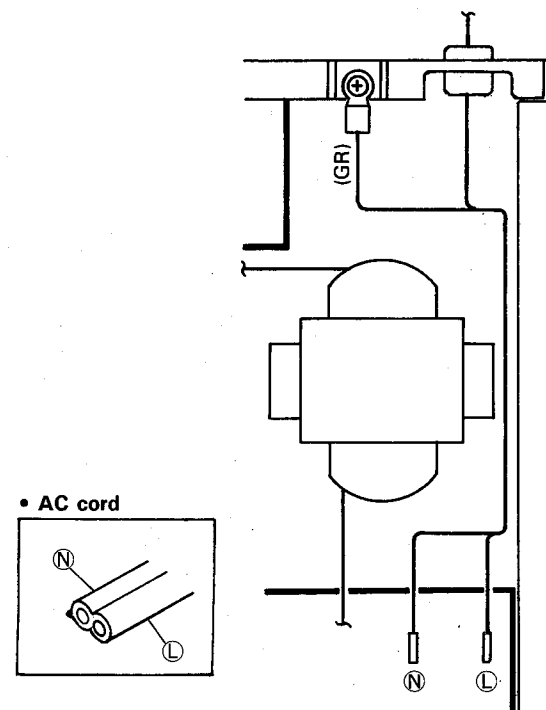
- ① -20dB/+4dB Input/Output Level Switch
- ② INPUT R & L (MONO) Jacks
- ③ OUTPUT R and OUTPUT L Jacks
- ④ TAP TEMPO/BYPASS Jack
- ⑤ MIDI IN Connector
- ⑥ MIDI OUT/THRU Switch
- ⑦ MIDI OUT/THRU Connector

- ① 入出力レベル切換スイッチ (-20dB/+4dB)
- ② INPUT端子 (R,L(MONO))
- ③ OUTPUT端子 (L,R)
- ④ フットスイッチ端子 (TAP TEMPO/BYPASS)
- ⑤ MIDI IN端子
- ⑥ MIDI OUT/THRU切換スイッチ
- ⑦ MIDI OUT/THRU端子

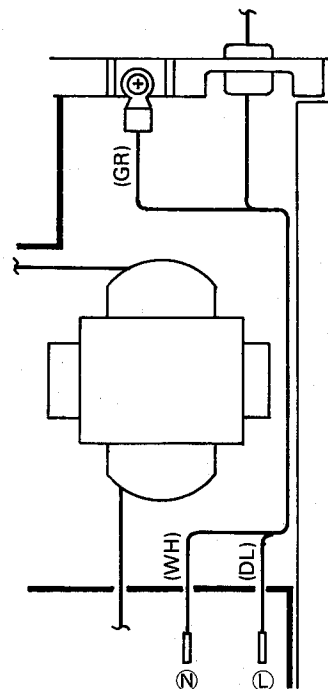
CIRCUIT BOARD LAYOUT (ユニットレイアウト)



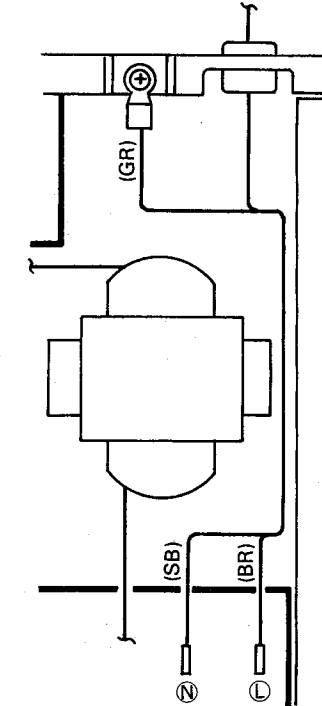
U.S. and
General export (110V) models



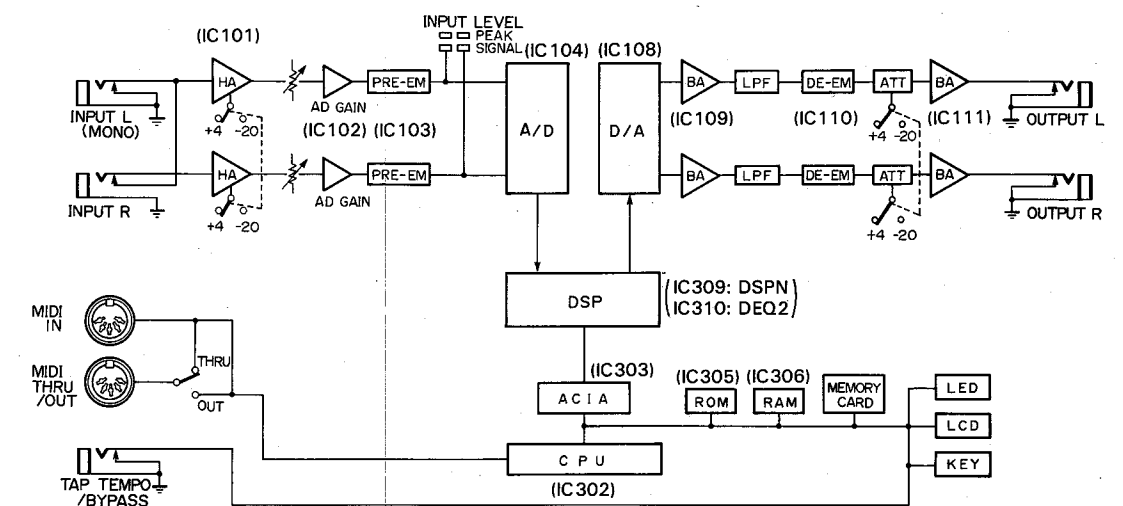
Canadian model



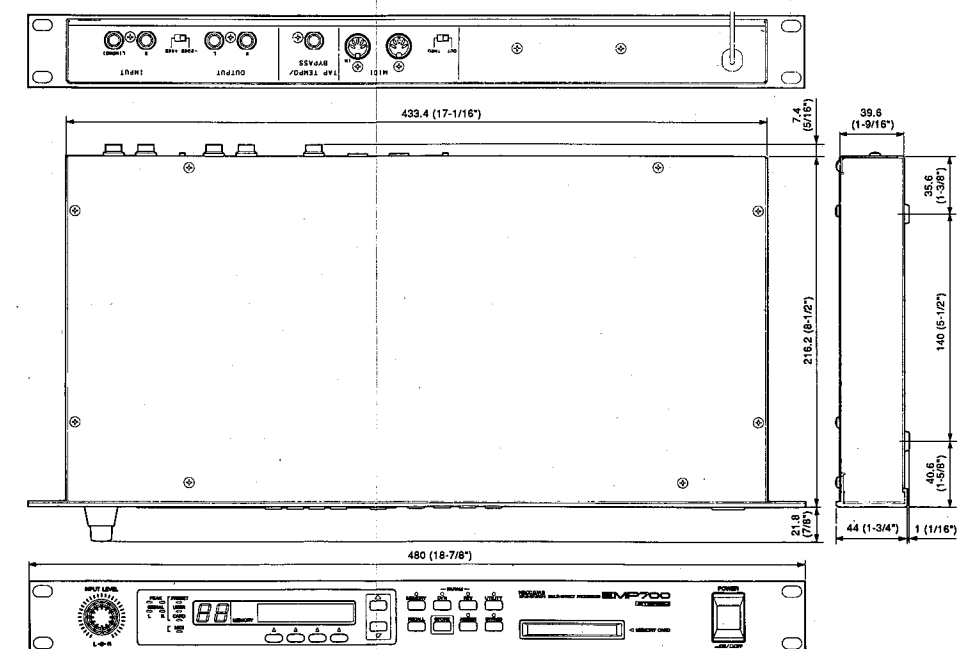
European model



BLOCK DIAGRAM (ブロック図)



DIMENSIONS (寸法図)



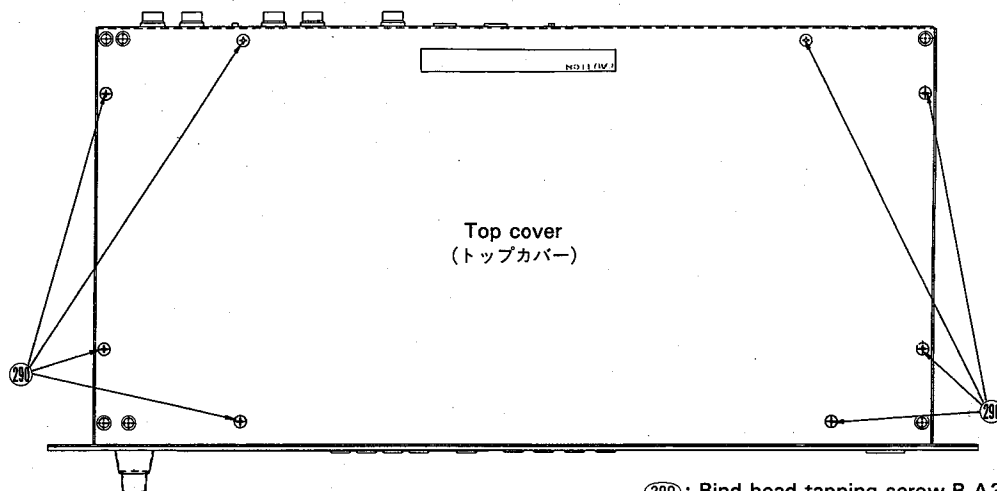
■ DISASSEMBLY PROCEDURE (分解手順)

1. Top Cover Removal

- 1-1. Remove the eight (8) screws marked as (290) in the figure, then the top cover can be removed. (Fig. 1)

1. トップカバーの外し方

- 1-1. (290)のネジ8本を外し、トップカバーを外します。
(図1)



(Fig. 1)

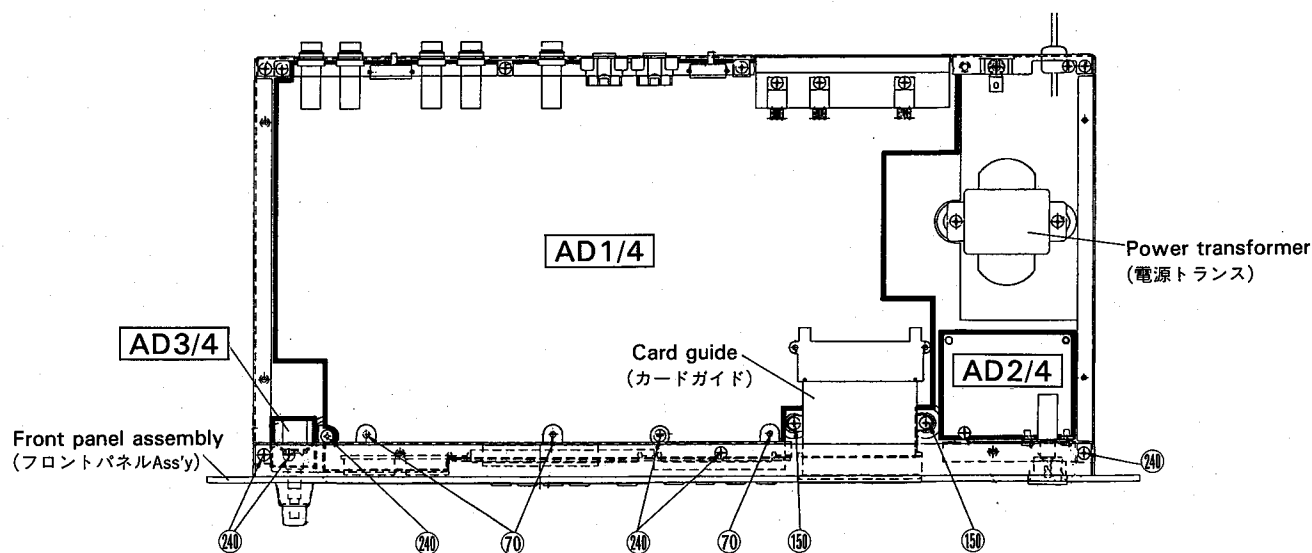
(290) : Bind head tapping screw-B A3.0×6 FCM3BL

2. Front Panel Assembly Removal

- 2-1. Remove the top cover. (see procedure 1)
2-2. Remove the six (6) screws marked (240), then the front panel assembly can be removed. (Fig. 2)

2. フロントパネルAss'yの外し方

- 2-1. トップカバーを外します。(1項参照)
2-2. (240)のネジ6本を外し、フロントパネルAss'yを外します。(図2)



(Fig. 2)

(70) : Bind head tapping screw-B A3.0×6 FCM3BL

(150) : Bind head tapping screw-B A3.0×6 FCM3BL

(240) : Bind head tapping screw-B A3.0×6 FCM3BL

3. LCD Unit Removal

- 3-1. Remove the top cover. (see procedure 1)
- 3-2. Remove the front panel assembly. (see procedure 2)
- 3-3. Remove the two (2) screws marked (150), five (5) screws marked (120) and two (2) screws marked (130). (Fig. 2 and Fig. 3)
- 3-4. Remove the three (3) screws marked (70). (Fig. 2)
- 3-5. Remove the three (3) plastic rivets marked (90) and straighten the part of the sub panel indicated with the arrow in the figure, then remove the sub panel. (Fig. 4)
- 3-6. Take the LCD unit out from the AD1/4 circuit board.

4. AD4/4 Circuit Board Removal

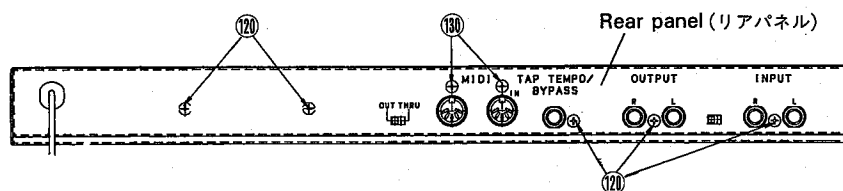
- 4-1. Remove the top cover. (see procedure 1)
- 4-2. Remove the front panel assembly. (see procedure 2)
- 4-3. Remove the two (2) screws marked (150), five (5) screws marked (120) and two (2) screws marked (130). (Fig. 2 and Fig. 3)
- 4-4. Remove the three (3) plastic rivets marked (90) and straighten the part of the sub panel indicated with the arrow in the figure, then remove the sub panel. (Fig. 4)
- 4-5. Take the AD4/4 circuit board out from the AD1/4 circuit board.

3. LCDユニットの外し方

- 3-1. トップカバーを外します。(1項参照)
- 3-2. フロントパネルAss'yを外します。(2項参照)
- 3-3. (150)のネジ2本を外し、リア側より(120)のネジ5本と(130)のネジ2本を外します。(図2、図3)
- 3-4. (70)のネジ3本を外します。(図2)
- 3-5. (90)のプラスチックリベット3個を外し、図中に矢印で示したサブパネルの金具をまっすぐにしてサブパネルを外します。(図4)
- 3-6. AD1/4シートからLCDユニットを外します。

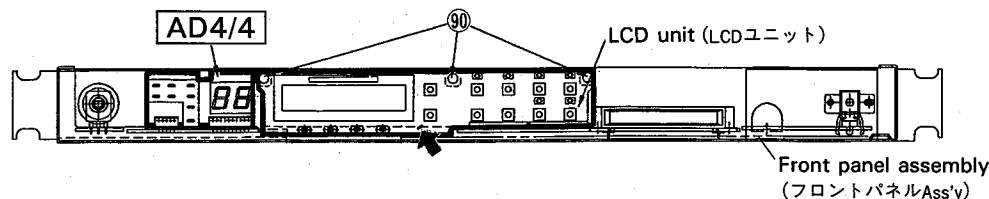
4. AD4/4シートの外し方

- 4-1. トップカバーを外します。(1項参照)
- 4-2. フロントパネルAss'yを外します。(2項参照)
- 4-3. (150)のネジ2本を外し、リア側より(120)のネジ5本と(130)のネジ2本を外します。(図2、図3)
- 4-4. (90)のプラスチックリベット3個を外し、図中に矢印で示したサブパネルの金具をまっすぐにしてサブパネルを外します。(図4)
- 4-5. AD1/4シートからAD4/4シートを外します。



(Fig. 3)

(120) : Bind head tapping screw-B A3.0×6 FCM3BL
 (130) : Bind head tapping screw-B A3.0×8 FCM3BL



(Fig. 4)

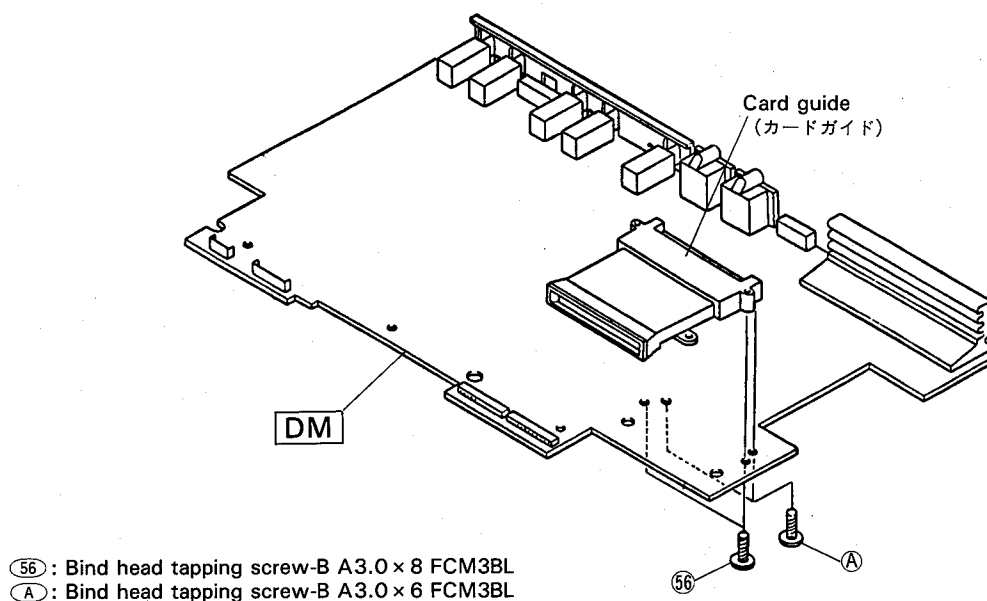
5. AD1/4 Circuit Board Removal

- 5-1. Remove the top cover. (see procedure 1)
- 5-2. Remove the front panel assembly. (see procedure 2)
- 5-3. Remove the LCD unit. (see procedure 3)
- 5-4. Remove the AD4/4 circuit board. (see procedure 4)
- 5-5. Remove the two (2) screws marked (56) and two (2) screws marked (A), then remove the card guide. (Fig. 5)

* The card guide is not a part of the AD1/4 circuit board.

5. AD1/4シートの外し方

- 5-1. トップカバーを外します。(1項参照)
- 5-2. フロントパネルAss'yを外します。(2項参照)
- 5-3. LCDユニットを外します。(3項参照)
- 5-4. AD4/4シートを外します。(4項参照)
- 5-5. (56)のネジ2本と(A)のネジ2本を外し、カードガイドを外します。(図5)
(カードガイドはAD1/4シートの構成部品ではありません。)



(Fig. 5)

6. AD3/4 Circuit Board Removal

- 6-1. Remove the top cover. (see procedure 1)
- 6-2. Remove the front panel assembly. (see procedure 2)
- 6-3. Remove the two (2) level control knobs marked (250) and (260), and loosen the hexagonal nut marked (160), then remove the AD3/4 circuit board. (Fig. 6)

7. AD3/4 Circuit Board Removal (Power Switch Removal)

- 7-1. Remove the top cover. (see procedure 1)
- 7-2. Remove the front panel assembly. (see procedure 2)
- 7-3. Pull out the power switch knob.
- 7-4. After the screw marked (140) and two (2) screws marked (145) have been removed, then the AD2/4 circuit board can be removed. (Fig. 6)

8. Power Transformer Removal

- 8-1. Remove the top cover. (see procedure 1)
- 8-2. Remove the two (2) screws marked (180), then the power transformer can be removed. (Fig. 6)

6. AD3/4シートの外し方

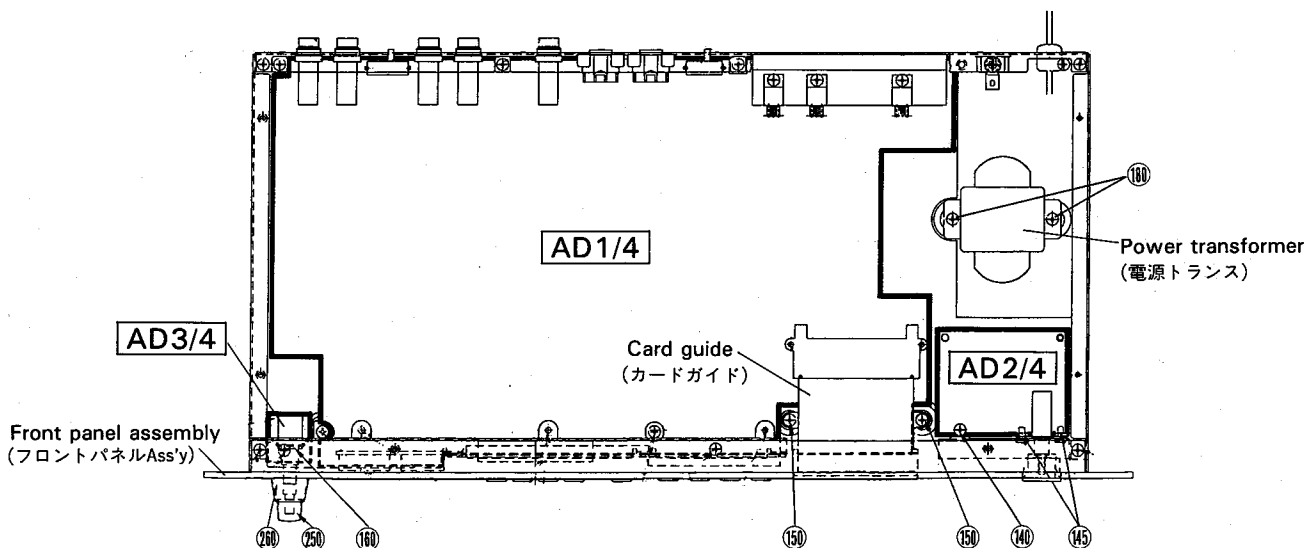
- 6-1. トップカバーを外します。(1項参照)
- 6-2. フロントパネルAss'yを外します。(2項参照)
- 6-3. (250)のVRつまみ(内)と(260)のVRつまみ(外)を外し、(160)の特殊六角ナットを緩めてAD3/4シートを外します。(図6)

7. AD2/4シート(パワースイッチ)の外し方

- 7-1. トップカバーを外します。(1項参照)
- 7-2. フロントパネルAss'yを外します。(2項参照)
- 7-3. パワースイッチつまみを外します。
- 7-4. (140)のネジ1本と(145)のネジ2本を外し、AD2/4シートを外します。(図6)

8. 電源トランスの外し方

- 8-1. トップカバーを外します。(1項参照)
- 8-2. (180)のネジ2本を外し、電源トランスを外します。(図6)



(Fig. 6)

- (140): Bind head tapping screw-B A3.0×6 FCM3BL
- (145): Bind head screw A3.0×6 FCM3BL
- (150): Bind head tapping screw-B A3.0×6 FCM3BL
- (160): Hexagonal nut φ9.0 FCM3BL
- (180): Bind head tapping screw-B 3.0×8 FCM3BL

LSI PIN DESCRIPTION (LSI端子機能表)

• HD63B03YP-N (XD245A00) CPU (Central Processing Unit)

PIN NO.	NAME	I/O	FUNCTION	PIN NO.	NAME	I/O	FUNCTION
1	Vss	I	Ground	33	A17	O	Address bus
2	XTAL	I	Clock	34	A16	O	
3	EXTAL	I		35	A15	O	
4	MP0	I	Mode program	36	A14	O	
5	MP1	I		37	A13	O	
6	RES	I	Reset	38	A11	O	
7	STBY	I	Stand-by mode signal	39	A10	O	
8	NMI	I	Non-maskable interrupt	40	A9	O	Ground
9	P20	I/O	Port 2	41	A8	O	
10	P21	I/O		42	Vss	O	
11	P22	I/O		43	A7	O	
12	P23	I/O		44	A6	O	Address bus
13	P24	I/O		45	A5	O	
14	P25	I/O		46	A4	O	
15	P26	I/O		47	A3	O	
16	P27	I/O	Port 5	48	A2	O	Data bus
17	P50	I/O		49	A1	O	
18	P51	I/O		50	A0	O	
19	P52	I/O		51	D7	I/O	
20	P53	I/O		52	D6	I/O	
21	P54	I/O		53	D5	I/O	
22	P55	I/O		54	D4	I/O	
23	P56	I/O		55	D3	I/O	
24	P57	I/O	Port 6	56	D2	I/O	
25	P60	I/O		57	D1	I/O	
26	P61	I/O		58	D0	I/O	
27	P62	I/O		59	BA	O	Bus available
28	P63	I/O		60	LIR	O	Load instruction register
29	P64	I/O		61	R/W	O	Read/Write control
30	P65	I/O		62	WR	O	Write control
31	P66	I/O		63	RD	O	Read control
32	P67	I/O		64	E	O	Enable

• HD63B50P (IG147300) ACIA (Asynchronous Communications Interface Adaptor)

Pin No.	Name	I/O	Function	Pin No.	Name	I/O	Function
1	Vss	I	Ground	13	R/W	I	Read/Write Enable
2	Rx Data	I	Receive data	14	E	I	
3	Rx CLK	I	Receive clock	15	D7	I/O	Data bus
4	Tx CLK	O	Transmit clock	16	D6	I/O	
5	RTS	I/O	Request to send	17	D5	I/O	
6	Tx Data	O	Transmit data	18	D4	I/O	
7	IRQ	I	Interrupt request	19	D3	I/O	
8	CS0	I	Chip select	20	D2	I/O	
9	CS2	I		21	D1	I/O	
10	CS1	I		22	D0	I/O	
11	RS	I	Resist select	23	DCD	I	Data carrier detect
12	Vcc	I	Power supply (+5V)	24	CTS	I	Clear to send

• **YSS208 (X1816A00) DSPN (Digital Signal Processor)**

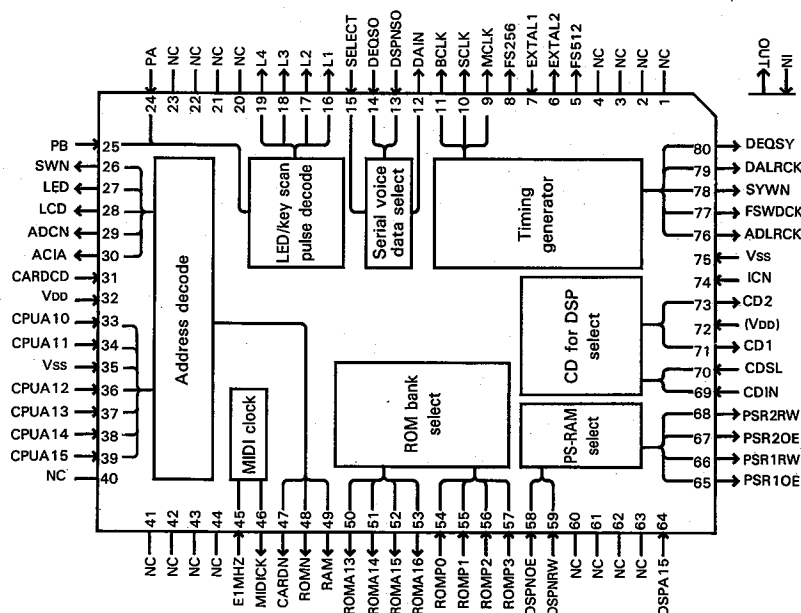
PIN NO.	NAME	I/O	FUNCTION	PIN NO.	NAME	I/O	FUNCTION
1	D9	I/O	External RAM data bus	33	A8	O	External RAM address bus
2	D8	I/O		34	A7	O	
3	D7	I/O		35	A6	O	
4	D6	I/O		36	A5	O	
5	D5	I/O		37	A4	O	
6	D4	I/O		38	A3	O	
7	D3	I/O		39	A2	O	
8	D2	I/O		40	A1	O	
9	D1	I/O	Ground	41	A0	O	Ground
10	Vss			42	Vss		
11	D0	I/O	Data input	43	TSTK	I	Test K
12	SI1	I		44	TST1	I	Test 1
13	SI0	I	Data output	45	CLKM	O	1/2 clock
14	SO1	O		46	SYW	I	Synch. signal input
15	SO0	O	ACIA synch. mode	47	CLK	I	Clock
16	XMD	I		48	CE	O	External RAM chip enable
17	XCLK	I	ACIA clock	49	IC	I	Initial clear
18	TO	O	Timer output	50	MDTST4	O	MOD data test
19	CRS	I	CDI reset	51	MDTST3	O	
20	CDO	O	Command output	52	MDTST2	O	
21	CDI	I	Command input	53	MDTST1	O	Wave add data input
22	TIM1	O	Timer 1	54	MDSI1	I	
23	OE	I	Output enable	55	MDSI0	I	Wave data output
24	R/W	O	Read/write	56	MDSO2	O	
25	A15	O	Power supply	57	MDSO1	O	Power supply
26	VDD			58	VDD		
27	A14	O	External RAM address bus	59	D15	I/O	External RAM data bus
28	A13	O		60	D14	I/O	
29	A12	O		61	D13	I/O	
30	A11	O		62	D12	I/O	
31	A10	O		63	D11	I/O	
32	A9	O		64	D10	I/O	

• **PCM66P (XG278A00) DAC (Digital Analog Converter)**

PIN NO.	NAME	I/O	FUNCTION	PIN NO.	NAME	I/O	FUNCTION
1	L/R CK	I	LR Clock Input	11	+Vcc		+Vcc
2	WD CK	I	Word Clock Input	12	+Vcc		+Vcc
3	CK	I	Clock Input	13	C REF		Reference Decouple
4	DATA	I	Data Input	14	Vref Sense	I	Reference Sense
5	NC			15	Vref	O	Reference Output
6	DIG GND		Digital Ground	16	+Vcc		+Vcc
7	ANA GND		Analog Ground	17	+Vcc		+Vcc
8	L-CH OUT	O	Left Channel Output	18	+Vcc		+Vcc
9	V COM		V Common	19	M1	I	Mode 1 Input
10	R-CH OUT	O	Right Channel Output	20	M2	I	Mode 2 Input

• YSS218-F (XJ875A00) XLTM (Timing Generator/Address Decoder/Selector)

PIN NO.	NAME	I/O	FUNCTION	PIN NO.	NAME	I/O	FUNCTION
1	NC			41	NC		
2	NC			42	NC		
3	NC			43	NC		
4	NC			44	NC		
5	FS512	O	Sampling freq. × 512	45	E1MHz	I	Clock, 1MHz
6	EXTAL1	I	Clock	46	M1DICK	O	MIDI clock, 500KHz
7	EXTAL2	O		47	CARDN	O	Card chip select
8	FS256	O	Sampling freq. × 256	48	ROMN	O	ROM chip select
9	MCLK	O	Sampling freq. × 128	49	RAM	O	RAM chip select
10	SCLK	O	Sampling freq. × 64	50	ROMA13	O	ROM address bus
11	BCLK	O	Sampling freq. × 64 (SCLK)	51	ROMA14	O	
12	DAIN	O	Data output (DSPNSO or DEQSO)	52	ROMA15	O	
13	DSPNSO	I	Data input from DSPN	53	ROMA16	O	
14	DEQSO	I	Data input from DEQ	54	ROMP0	I	Bank select
15	SELECT	I	Input select (0: DSPNSO 1: DEQSO)	55	ROMP1	I	
16	L1	O	LED/key scan pulse	56	ROMP2	I	
17	L2	O		57	ROMP3	I	
18	L3	O		58	DSPNOE	I	DSP-RAM output enable
19	L4	O		59	DSPNRW	I	DSP-RAM write pulse
20	NC			60	NC		
21	NC			61	NC		
22	NC			62	NC		
23	NC			63	NC		
24	PA	I	LED/key scan input (bit 0)	64	DSPA15	I	DSP-RAM address bus
25	PB	I	LED/key scan input (bit 1)	65	PSR1OE	O	DSP-RAM1 output enable
26	SWN	O	Key data input enable	66	PSR1RW	O	DSP-RAM1 write pulse
27	LED	O	LED data enable	67	PSR2OE	O	DSP-RAM2 output enable
28	LCD	O	LCD data enable	68	PSR2RW	O	DSP-RAM2 write pulse
29	ADCN	O	ADC enable	69	CDIN	I	Control data input
30	ACIA	O	ACIA enable	70	CDS	I	Control data output select
31	CARDCD	I	RAM card detection	71	CD1	O	Control data output 1
32	VDD		Power supply	72	VDD		Power supply
33	CPUA10	I	(Ground)	73	CD2	O	Control data output 2
34	CPUA11	I		74	ICN	I	Reset
35	VSS			75	VSS		Ground
36	CPUA12	I		76	ADLRCK	O	ADC data select (1: L 0: R)
37	CPUA13	I	CPU address bus	77	FSWDCK	O	Sampling freq. × 2
38	CPUA14	I		78	SYWN	O	Synch. signal
39	CPUA15	I		79	DALRCK	O	DAC data L/R latch signal
40	NC			80	DEQSY	O	Synch. signal for DEQ



• **YM6104 (XE788A00) DEQ2 (Digital Equalizer)**

Pin No.	Name	I/O	Function	Pin No.	Name	I/O	Function
1	VDD	I	+5V	12	Vss	I	Earth (Ground)
2	XHD	I	Alteration of Sync. (=+5V) or Asynch. (=0V) for CDI input terminal (Synch: 1:1, Asynch: 16:1)	13, 14	S10, S11	I	INPUT for Serial data signal
3	CRS	I	Initialized Serial Control Interface	15, 16	SO0, SO1	O	OUTPUT for Serial data signal
4	CDI	I	Inputs of μ PGM, Para, Ser. Cont. Data of Control Reg.	17	OVF	O	Detector for OVER Flow
5	CDO	O	Outputs of μ PGM, Para, Ser Cont. Data of Control Reg.	18	TEST	I	For test. Normally connecting to +5V
6	XCLK	I	In/Out clock for CDI & CDO	19	C2	O	Output is delayed Data of 2nd bit of P. Reg. by 1 bit.
7	TRG	I	Determines transmit timing of PARA. to Para. Reg. from T BFR.	20	C1	O	Output is delayed Data of 1st bit of P. Reg. by 1 bit.
8	ESL	I	Timing determination of data for External at Ext. Shift CLK	21	C0	O	Output is delayed Data of 0 bit of P. Reg. by 1 bit.
9	ELD	I	Timing determination of data for Inner at Ext. Shift CLK	22	CEMD	I	+5V: It's necessary to input 2 Byte for CE to CDI 0V: It needs not to have a data for CE to CDI
10	ECLK	I	Input Shift CLK of IN/OUT SR at Ext Shift CLK	23	IC	I	Initialized for DEQ
11	CLK	I	System Clock	24	SYW	I	Synchro. signal for system

• **AK5339-VP (XI112A00) DAC (Digital Analog Converter)**

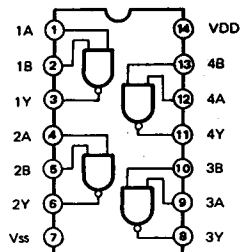
PIN NO.	NAME	I/O	FUNCTION	PIN NO.	NAME	I/O	FUNCTION
1	AGND	I	Analog ground	15	SCLK	I	Serial output data clock
2	AINL	I	Left channel analog input	16	SDATA	O	Serial data output
3	ZEROL	I	Zero level input for left channel	17	FSYNC	I	FSYNC signal input
4	VA+	I	Positive analog power supply	18	VD+	I	Positive digital power supply
5	VA-	I	Negative analog power supply	19	DGND	I	Digital ground
6	APD	I	Analog power down	20	CLK	I	Digital section input clock
7	ACAL	I	Analog calibrate	21	OCLK	O	Clock output
8	NC	I	No connection	22	NC	I	NC
9	DCAL	O	Digital calibrate output	23	CLKIN	I	Master input clock
10	DPD	I	Digital power down	24	LGND	I	Logic ground
11	TST	I	Test inputs	25	VL+	I	Positive logic power supply
12	CMODE	I		26	ZEROR	I	Zero level input for right channel
13	SMODE	I	Left/Right select	27	AINR	I	Right channel analog input
14	L/R	I		28	VREF	O	Voltage reference output

■ **IC BLOCK DIAGRAM (ICブロック図)**

• **TC74HC00AP (IR0000000)**

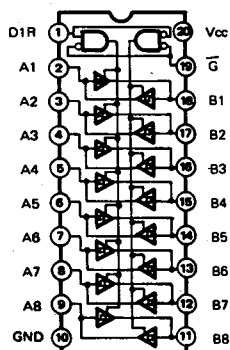
• **SN74HC00N (IR000050)**

Quad 2 Input NAND



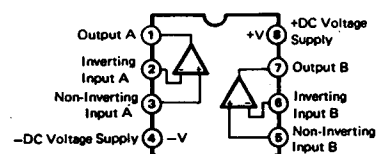
• **TC74HC245AP (IR024500)**

Octal 3-State Bus Transceiver



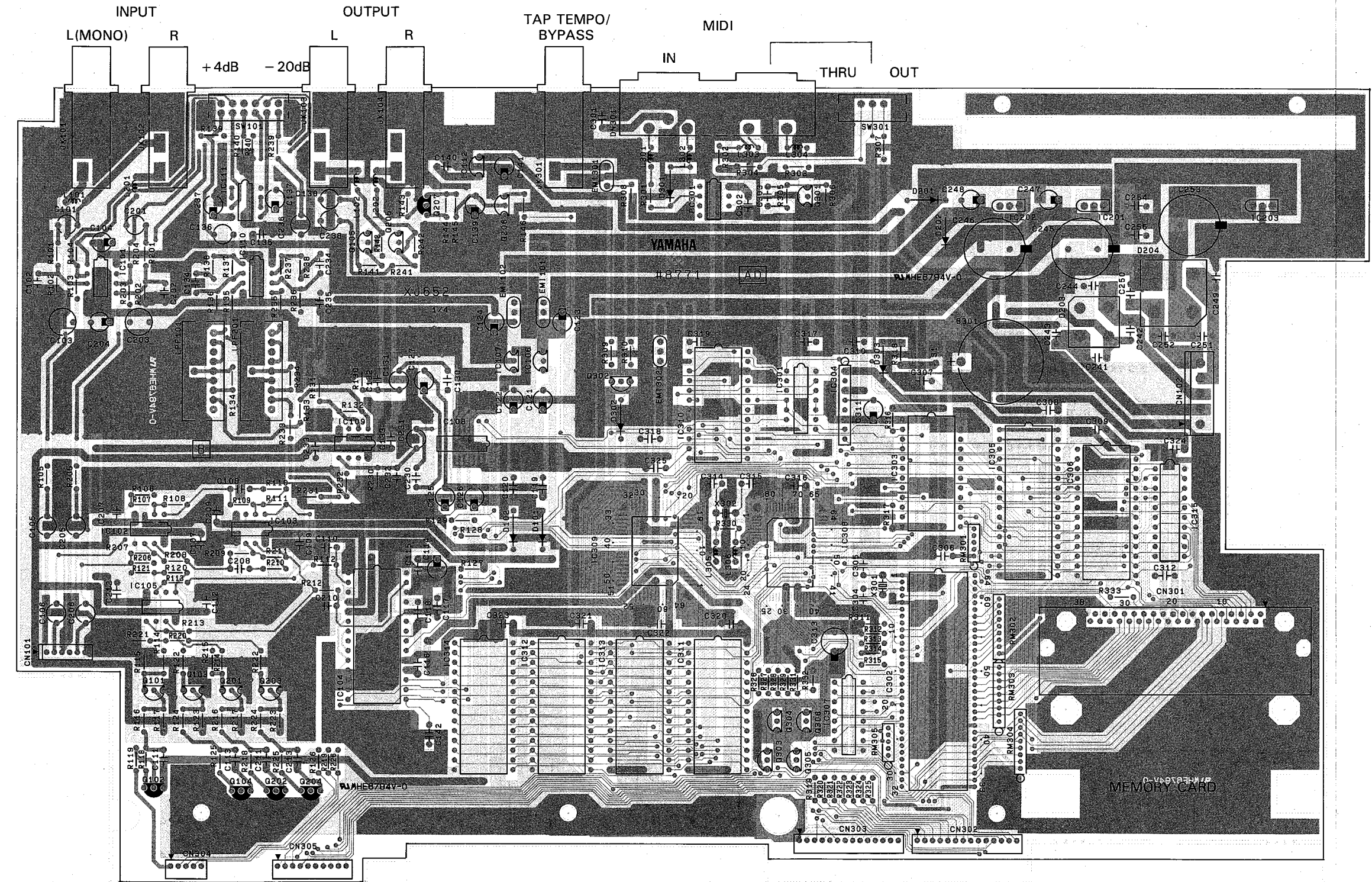
• **RC4558D-V (IG001390)**

Dual Operational Amplifier



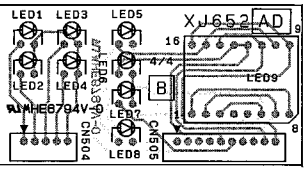
■ CIRCUIT BOARD (シート基板図)

● AD1/4 Circuit Board



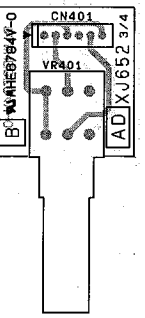
Components side (部品側)

● AD2/4 Circuit Board



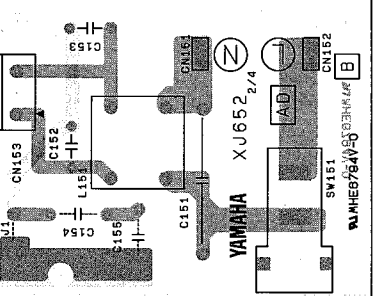
Components side (部品側)

● AD3/4 Circuit Board



Components side (部品側)

● AD4/4 Circuit Board



Components side (部品側)

Notes)

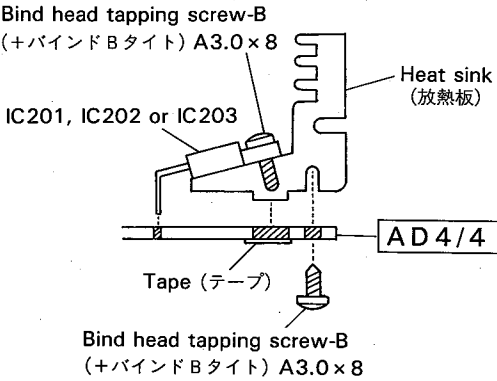
- Circuit Board: AD (VL379000) XJ652A0 J,U,C,V
AD (VL379100) XJ652A0 H,B
1. IC
IC101~103, 105,109~111: RC4558D-V (IG001390) OP AMP.
IC104: AK5339-VP (X1112A00) ADC
IC106: μ PC78L05J (XC349A00) 5V REGULATOR
IC107: NJM79L05A (IG130500) -5V REGULATOR
IC108: PCM66P (XG278A00) DAC
IC112: NJM78L12A (XD066A00) 12V REGULATOR
IC201: NJM7812FA (XC720A00) 12V REGULATOR
IC202: NJM7912FA (XC721A00) -12V REGULATOR
IC203: NJM7805FA (XC719A00) 5V REGULATOR
IC301: TC74HC00AP (IR000000) NAND or SN74HC00N (IR000050) NAND
IC302: HD63B03YP-N (XD245A00) CPU
IC303: HD63B50P (IG147300) ACIA
IC304: M62021L (XH970A00) RESET (XK356A00) 1M EPROM
IC306: LC3664RL-12 (XG517A00) SRAM 64K
IC308: YSS218-F (XJ875A00) XLTM
IC309: YSS208 (XJ816A00) DSPN
IC310: YM6104 (XE788A00) DEQ2
IC311~314: TC51832PL-10 (XC628A00) PSRAM 256K or HM65256BLP-10 (XH116A00) PSRAM 256K
IC315: TC74HC245AP (IR024500) BUS BUFFER
2. Photo Coupler
PC301: 6N137 (VD473200)
3. Transistor
Q101,103,201, 203,301,302: 2SC1815 Y (IC1815I0)
Q102,104, 202,204,207: 2SA1015 Y (IA1015I0)
Q105,205,206: 2SC2878 B (VC710400)
Q303~306: 2SC1213A D (IC121340)
4. Transistor Array
IC307: TD62506P (IG138700)
5. Diode
D101,102,201,202: 11ES4 (VB481900)
D301~303: 1SS133,1SS176 (VB941200)
6. Diode Stack
D203: S2VB20 2A 200V (IH001120)
D204: 4D4B41 4A 200V (IH000870)
7. LED
LED 1,3,8: GL8HD26 RE (VK018900) PEAK(L,R),MIDI
LED 2,4~7: GL8KG26 GR (VJ734900) SIGNAL(L,R),PRESET, USER,CARD
8. LED Display
LED 9: LN524RKS (VA026000)
9. Resistor Array
RM301,305: RGLE4X103J (VF773500)
RM302~304: RGLE8X103J (VF771900)
10. Variable Resistor
VR401: A10K $\times$ 2 RK124222 (VL962700) INPUT LEVEL(L,R)

11. Electrolytic Cap.
C245,246: 2200 μ F 25V (UJ749220)
C253: 2200 μ F 16V (UJ739220)
12. Ceramic Cap.
C151: 0.1 μ F (FR203100)
C152,153: 2200pF 400V (FI383220)
C154,155: 4700pF 400V (FI383470) H,B
13. Semiconductive Cera. Cap.
0.1 μ F 25V Z (VC694800)
14. Coil
L101,102,201, 202,301~304: FL5R200QNT (VB835000) 20 μ H
L151: PLA3021A 3mm (GD900760)
15. LC Filter
LPF101,201: LPF 20KHZ (VH408900)
16. EMI Filter
EMI101,102, 301,302: LS MT Y223NB (FZ006970)
17. Ferrite Bead
L305,306: BL02RN1-R62T4 (GE300610)
18. Ceramic Resonator
X301: 4MHz CSA4.00MG (QU004800)
X302: CSA22.5792MG (VH409300)
19. Thermistor
R332: ERT-D2FK103S1K (VN140900)
20. Push Switch
SW151: ESB-82TYPE (VJ557300) POWER SWITCH
21. Slide Switch
SW101: SSSU142-S06S-0 (VM475900) -20dB, +4dB
SW301: SSSU112-S06S-0 (VM476100) MIDI OUT/THRU
22. DIN Jack
DN301: 5P3 YKF51-50 (VK519000) MIDI(IN,OUT/THRU)
23. Phone Jack
JK101~104,301: YKB21-5012 (VB312600) INPUT(L,R), OUTPUT(L,R),TAP TEMPO/BYPASS
24. Connector, Card
CN301: IC3A38PS-1.27D 38P (VF821100) MEMORY CARD
25. Lithium Battery
B301: SONY/CR2032 (VE338400)
26. Terminal
CN151,152: (VA855400)

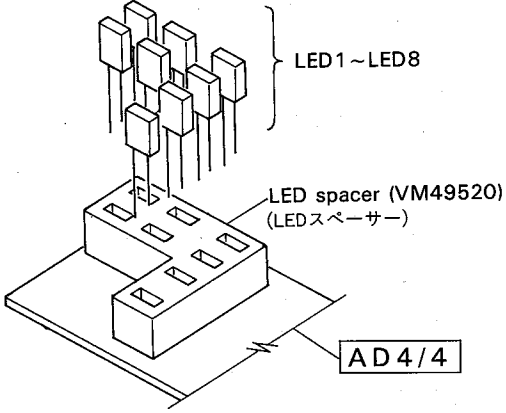
	J1	C154	C155
VL379000 (J,U,C,V)	○	×	×
VL379100 (H,B)	×	○	○

(○: installed ×: not installed)

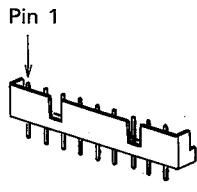
- IC201, IC202 and IC203 installation
(IC201~IC203の取り付け)



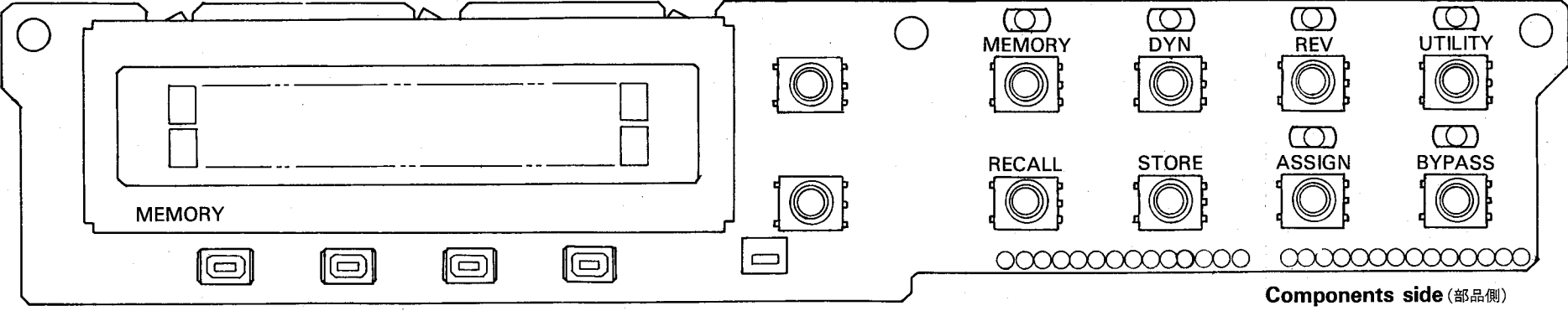
- LED1~LED8 installation
(LED1~LED8の取り付け)



- CN304 and CN305



• LCD UNIT



Notes)

- LCD Unit: (VL842500)
1. IC
IC1: NJU64720-02
2. LED
LED 1~6: TLR220 RE (VE464300)
3. LED Back-lit
LED 7:
4. Tact Switch
SW 1~10: SKHUQB
SW11~14: SKHLAC023A (VC021100)

■ TEST PROGRAM

A. HOW TO ENTER THE TEST PROGRAM

While pressing the [Function 1] key and [DYN] key, turn on the power switch.

B. PROCEEDING THROUGH THE TESTS

When you have entered the test program, select a test number by using the ▲ and ▼ keys, and then press the [RECALL] key to execute the test.

C. EXIT TEST PROGRAM

To exit the test program mode and return to normal operation, select the test number "50", then press the [RECALL] key. Activating the test 7 after performing tests 1 through 5 will restore normal operation too.

If the test 7 is executed without completion of tests 1 through 6, "CHECK NOT END" message will appear on the LCD, and the test that are performed will be shown by following LED switch indicators:

TEST 1: [MEMORY]
TEST 2: [DYN]
TEST 3: [REV]
TEST 4: [UTILITY]
TEST 5: [ASSIGN]
TEST 6: [BYPASS]

C. INITIAL TEST

After the system has entered the test program, the ACIA check will be performed automatically and a signal passes through the digital effect circuit. When the test checks OK, the LCD display will indicate "TEST ACIA. OK".

(The SRAM check is performed automatically when the power is applied to the unit on normal operation.)

TEST 1. LCD TEST

Check that all dots of the LCD turn ON and OFF five times, then the TEST END message will appear on the LCD.

```
DIAGNOSIS V1.0
TEST LCD      END
```

TEST 2. LED ON/OFF TEST

Check that each LED blinks once in succession from the left end of the unit.

First, check that 7-segment LED will display in sequence numbers "00" through "99", then the PRESET, USER, CARD and MIDI LED indicators blink one after another, and each switch LED blinks once in succession.

Next, verify all LEDs light and then turn off together, finally, 7-segment LED will show "2". The LEVEL indicators will remain OFF during this test.

TEST 3. PANEL AND FOOT SWITCH TEST

Press the panel switches consecutively from the [Function 1] switch to foot switch [TAP TEMPO/BYPASS], according to the order indicated by the LCD.

```
DIAGNOSIS V1.0
TEST SWITCH F1
```

(e.g. When checking [Function 1].)

If the switch is OK, you should proceed to the next switch. If the wrong switch is pressed, the error message NG will be displayed. At this time, press the [RECALL] key to initiate this test.

```
DIAGNOSIS V1.0
TEST SWITCH NG
```

When the switch name "TAP" is displayed on the LCD, attach a foot switch to the TAP TEMPO/BYPASS jack on the rear panel, then press it to check. If checks OK, 'OK' is displayed on the LCD and the test will end.

```
DIAGNOSIS V1.0
TEST SWITCH OK
```

TEST 4. MEMORY CARD TEST

This test performs a read/write test on the RAM card, a card insert test and a write protect switch test. Insert a RAM card with the memory protect switch turned off and execute the test.

DISPLAY OF TEST RESULTS

OK

```
DIAGNOSIS V1.0
TEST CARD  R/W
```

NG

```
DIAGNOSIS V1.0
TEST CARD  NG
```

Then check that when you remove the card, the message on the display will be as follow:

```
DIAGNOSIS V1.0
TEST CARD  NON
```


Next, check that when the memory protect switch is set from "protect off" to "protect on" and insert the card back into the slot, the display will show the following message.

```
DIAGNOSIS V1.0
TEST CARD PRO
```

TEST 5. MIDI TEST

After connecting the MIDI IN to the MIDI OUT via a MIDI cable, execute the test. The test results will be displayed on the LCD.

```
DIAGNOSIS V1.0
TEST MIDI OK
```

(e.g. When the test is OK.)

```
DIAGNOSIS V1.0
TEST MIDI NG
```

(e.g. When unexpected data was received.)

```
DIAGNOSIS V1.0
TEST MIDI NG
```

(e.g. When no data was received.)

TEST 6. FACTORY SET TEST

This test is used to initialize the data to the factory settings.

When this test is executed, the following display will appear.

```
DIAGNOSIS V1.0
RAM INITIALIZE?
```

If you press the [STORE] key, the factory preset data will be restored, the LCD will display the message shown below.

```
DIAGNOSIS V1.0
RAM INITIALIZE
```

TEST 7. DEQ2 CHIP TEST

Check that a correct sine wave of 880Hz, 12dBm is output using an oscilloscope.

```
DIAGNOSIS V1.0
TEST DEQ2
```

TEST 8. DSPN CHIP TEST

Check that a correct sine wave of 880Hz, 12dBm is output using an oscilloscope.

```
DIAGNOSIS V1.0
TEST DSPN
```

■ INITIALIZATION

While pressing the [Function 1] key and [▲] key, turn on the power switch, then the RAM data will be initialized and other parameters are set with the factory setting data.

■ INSPECTIONS

Before performing any following adjustments, set the unit as follows:

1. Input level controls: maximum
2. Set the $-20\text{dB}/+4\text{dB}$ switch at $+4\text{dB}$
3. Short the L and R outputs with 10kohm loads.
4. BYPASS switch: ON

1. Gain test

Check that the OUTPUT should be $-10\text{dBm} \pm 1.5\text{dB}$, when a sine wave of 100Hz at -20dBm is applied to the INPUT L.

When the $-20\text{dB}/+4\text{dB}$ switch is turn to -20dB , the OUTPUT level should also be $-10\text{dBm} \pm 1.5\text{dB}$.

2. Frequency response test

When a sine wave of 0dBm is applied to the INPUT L, check that the output is as follows. (taking 1kHz as a reference)

20Hz ~ 5kHz	$\pm 1.5\text{dB}$
6kHz ~ 18kHz	$\pm 1.5\text{dB}$
24kHz	less than -10dB

3. Residual noise test

When the input is opened, residual noise should be less than -67dBm .

(Use a 12.7kHz , -6dB/oct. filter)

4. Maximum output level, distortion factor and channel separation test

Check that the output is $+17\text{dBm}$ when a sine wave of 1kHz is applied, and when the input level is adjusted, making the distortion rate less than 0.03% .

Then increase the input level to obtain the output of $+18\text{dBm}$, check that the distortion rate is less than 0.1% .

Next, Apply no signal to the INPUT L, check that the L OUTPUT level should be less than -50dBm .

(Check the R channel in same manner.)

5. Measuring instruments

1. For the distortion measurement, a low-pass filter with cut-off frequency of 80kHz , -6dB/oct. must be used.
2. For the noise level measurement, a low-pass filter with cut-off frequency of 12.7kHz , -6dB/oct. must be used.
3. The output impedance of the signal generator must be less than 600ohms .
4. The input impedance of the measuring instruments must be over 1Mohms .

■ テストプログラム

テストプログラムの起動

[F1]と[DYN]キーを押しながら、電源スイッチをONします。

テストプログラムの進め方

[▲]と[▼]キーを使用して実行するテスト番号を選択した後、[RECALL]キーを押してテストを実行します。

テストの終了の仕方

テスト50を実行すると、テストプログラムモードを抜けて通常モードとなります。また、テスト1からテスト5までを全て終了した後にテスト7を実施しても、テストプログラムを終えることができます。テスト1からテスト5までを終了せずにテスト7を実施すると、“CHECK NOT END”がLCDに表示されると共に、以下に示すスイッチのLEDが点灯し、終了したテストを示します。

テスト1：[MEMORY] LED

テスト2：[DYN] LED

テスト3：[REV] LED

テスト4：[UTILITY] LED

テスト5：[ASSIGN] LED

テスト6：[BYPASS] LED

A. イニシャルテスト

テストプログラムが起動されると、LSIの回線チェックが実行されます。

テストがOKなら、“TEST ACIA. OK”がLCDに表示されます。

(SRAMチェックは、通常動作時の電源スイッチONのときに、実行されます。)

なお、テストプログラムが起動されると、AD/DA回路はダイレクト信号のみをOUTPUT LとRに出力します。

テスト1 LCD表示器の動作チェック

テストが起動されると、LCDの全ドットが5回点滅し、その後、次の画面が表示されます。

```
DIAGNOSIS V1.0
TEST LCD      END
```

テスト2 LEDの点灯チェック

LEDが全て点灯するか、目視によりチェックします。

1. メモリーLEDが、“00”、“11”、“22”と順次点灯します。
2. [PRESET]、[USER]、[CARD]、[MIDI]のLEDが、順次点灯します。
3. スイッチ上のLEDが、1個ずつ順次点灯します。
4. 全LEDが点灯します。(レベルメーター用のLEDは除く)
5. LEDが消灯し、メモリーLEDが“2”を表示して停止します。

テスト3 スイッチの動作確認

テストが起動されると、次の画面がLCDに表示されます。

```
DIAGNOSIS V1.0
TEST SWITCH F1
```

(F1の部分は、点滅している)

1. [F1]キーを押すと、[F1]のブリンクが[F2]に変わります。
2. [F2]キーを押すと、[F2]のブリンクが[F3]に変わります。

以下、LCDの表示に従ってスイッチを順番に押していきます。

3. [BYPASS]キーを押すと、[TAP]のブリンクに変わります。そうしたら、[TAP TEMPO/BYPASS]のフットスイッチ用ジャックにフットスイッチを接続し、ONします。

テストがOKなら、次の画面がLCDに表示されます。

```
DIAGNOSIS V1.0
TEST SWITCH OK
```

スイッチを押し間違えたときは、テストを再起動してやり直して下さい。

テスト4 メモリーカードのI/Oポートのチェック

メモリーカードのライトプロテクトスイッチをOFFにして、テストを起動します。

カードに書き込み、読み出しができた場合

```
DIAGNOSIS V1.0
TEST CARD R/W
```

カードに書き込み、読み出しができなかった場合

```
DIAGNOSIS V1.0
TEST CARD NG
```

次に、メモリーカードをスロットから抜きます。これを確認できたときは、次のように表示されます。

```
DIAGNOSIS V1.0
TEST CARD NON
```

さらに、メモリーカードのライトプロテクトスイッチをONにして、もう一度差し込みます。これを確認できた場合は、次のように表示されます。

```
DIAGNOSIS V1.0
TEST CARD PRO
```

手順を間違えたときは“NG”となるので、テストを再起動してやり直して下さい。

テスト5 MIDIの入出力チェック

MIDI INとMIDI OUTをMIDIケーブルで接続した後、テストを起動します。

テストがOKのとき

```
DIAGNOSIS V1.0
TEST MIDI OK
```

MIDI OUTから出力された信号がMIDI INを経由してCPUに戻ってこないとき

```
DIAGNOSIS V1.0
TEST MIDI NG
```

信号は戻ってくるが、正常でないとき

```
DIAGNOSIS V1.0
TEST MIDI NG
```

テスト6 ユーザーRAMの初期設定

テストが起動されると、次の画面が表示されます。

```
DIAGNOSIS V1.0
RAM INITIALIZE?
```

[STORE] キーを押すと、ユーザーRAM領域にファクトリープリセット値がセットされると共に、各パラメータ値も初期値に設定され、LCD画面は次のように変わります。

```
DIAGNOSIS V1.0
RAM INITIALIZE
```

テスト7 DEQ2-LSIのチェック

テストが起動されるとDEQ2から約880Hz、12dBmの正弦波が出力されるので、これをオシロスコープで観測してLSIが正常かどうか判断します。テスト中は、次の画面が表示されます。

```
DIAGNOSIS V1.0
TEST DEQ2
```

テスト8 DSPN-LSIのチェック

テストが起動されるとDSPNから約880Hz、12dBmの正弦波が出力されるので、これをオシロスコープで観測してLSIが正常かどうか判断します。テスト中は、次の画面が表示されます。

```
DIAGNOSIS V1.0
TEST DSPN
```

■RAMのイニシャライズ

[F1] と [▲] キーを押しながら電源スイッチをONすると、RAMのデータはイニシャライズされ、その他のパラメータも初期値に設定されます。

■ 検査

・準備

特に指定のない限り、パネルのボリュームおよびスイッチは、下記の状態とする。

1. INPUTレベルコントロール(L、R) : 最大
2. +4dB/-20dBスイッチ : +4dB
3. BYPASSキー : ON
4. OUTPUT(L、R)端子に10k Ω の負荷を接続する

1. 利得

INPUT(L)より100Hz/-20dBmの信号を加えたとき、+4dB/-20dBスイッチがいずれの側に設定されていても、OUTPUT(L、R)端子には-10dBm $\pm$ 1.5dBの出力が得られること。

2. 周波数特性

INPUT(L)より0dBm程度の信号を加えたとき、OUTPUT(L、R)端子の出力信号の周波数特性は、1kHzを基準として下表の範囲にあること。

20Hz-5kHz	$\pm$ 1.5dB
6kHz-18kHz	$\pm$ 1.5dB
24kHz	-10dB以下

3. ノイズレベル

INPUT端子に接続されているプラグを抜いたとき、OUTPUT(L、R)端子でのノイズレベルは-67dBm以下のこと。(12.7kHz、-6dB/octのフィルターを使用すること)

4. 最大出力、歪率、チャンネルセパレーション

INPUT(L、R)端子それぞれに1kHzの信号を入力します。入力信号のレベルを徐々に大きくしていったとき、OUTPUT(L、R)端子には+17dBmの出力が歪率0.03%以内で得られること。また、出力が+18dBmのときの歪率は1%以内のこと。

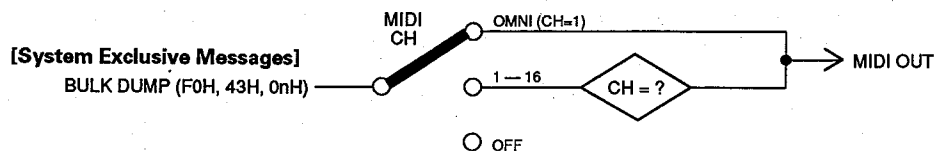
このとき、INPUT(L)端子に加えられている信号をOFFすると、OUTPUT(L)端子の出力信号レベルは-50dBm以下のこと。次に、INPUT(L)端子にもう一度信号を加えた後、INPUT(R)端子に加えられている信号をOFFすると、OUTPUT(R)端子の出力信号レベルは-50dBm以下のこと。

4 測定器

- 1 歪率測定時は、80kHz、-6dB/octのフィルターを使用すること。
- 2 ノイズレベル測定時は、12.7kHz、-6dB/octのフィルターを使用すること。
- 3 発信器の出力インピーダンスは、600 Ω 以下のこと。
- 4 測定器の入力インピーダンスは、1M Ω 以上のこと。

MIDI DATA FORMAT

1. TRANSMISSION CONDITIONS



2. TRANSMISSION DATA

2-1. System Information

[1] System Exclusive Messages

• BULK DUMP

Bulk dump messages can be transmitted when the MIDI OUT/THRU select switch of the EMP700 is set to the "OUT" position.

The combination of bulk dump data to be transmitted can be selected in the utility mode.

1) 1 MEMORY BULK DATA

When a 1 MEMORY BULK OUT operation is performed or when a 1 MEMORY BULK DUMP REQUEST message is received by the EMP700, the data is transmitted on the MIDI channel specified for the currently selected BANK.

STATUS	11110000 (F0H)	SYSTEM EXCLUSIVE
ID NO.	01000011 (43H)	YAMAHA
SUB STATUS	0000nnnn	nnnn = CHANNEL NO. *1
FORMAT NO.	01111110 (7EH)	UNIVERSAL BULK DUMP
BYTE COUNT	00000001 (01H)	HEADER & DATA = 168 bytes
	00101000 (28H)	
HEADER	01001100 (4CH)	"L"
	01001101 (4DH)	"M"
	00100000 (20H)	" "
	00100000 (20H)	" "
	00111000 (38H)	"8"
	00110111 (37H)	"7"
	00110111 (37H)	"7"
	00110001 (31H)	"1"
DATA NAME	01001101 (4DH)	"M" (1 MEMORY DATA)
MEMORY NO.	0nnnnnnnn	nnnnnnnn = USER MEMORY NO. *8
DATA	0000dddd	1st byte *9
	:	:
	:	:
	0000dddd	160th byte
CHECKSUM	0eeeeeee	*10
EOX	11110111 (F7H)	

2) 1 BANK PROGRAM CHANGE TABLE BULK DATA

When a 1 BANK PROGRAM CHANGE TABLE BULK OUT operation is performed or when a 1 BANK PROGRAM CHANGE TABLE BULK DUMP REQUEST message is received by the EMP700, the data is transmitted on the MIDI channel specified for the currently selected BANK.

STATUS	11110000 (F0H)	SYSTEM EXCLUSIVE
ID NO.	01000011 (43H)	YAMAHA
SUB STATUS	0000nnnn	nnnn = CHANNEL NO. *1
FORMAT NO.	01111110 (7EH)	UNIVERSAL BULK DUMP
BYTE COUNT	00000010 (02H)	HEADER & DATA = 266 bytes
	00001010 (0AH)	
HEADER	01001100 (4CH)	"L"
	01001101 (4DH)	"M"
	00100000 (20H)	" "
	00100000 (20H)	" "
	00111000 (38H)	"8"
	00110111 (37H)	"7"
	00110111 (37H)	"7"
	00110001 (31H)	"1"
DATA NAME	01010100 (54H)	"T" (1BANK DATA)
BANK NO.	00000bbb	bbb = BANK NO. *11
DATA	00000bbb	1st byte *12
	:	:
	:	:
	00000bbb	256th byte
CHECKSUM	0eeeeeee	*10
EOX	11110111 (F7H)	

3) SYSTEM SETUP BULK DATA

When a SYSTEM SETUP BULK OUT operation is performed or when a SYSTEM SETUP BULK DUMP REQUEST message is received by the EMP700, the data is transmitted on the MIDI channel specified for the currently selected BANK.

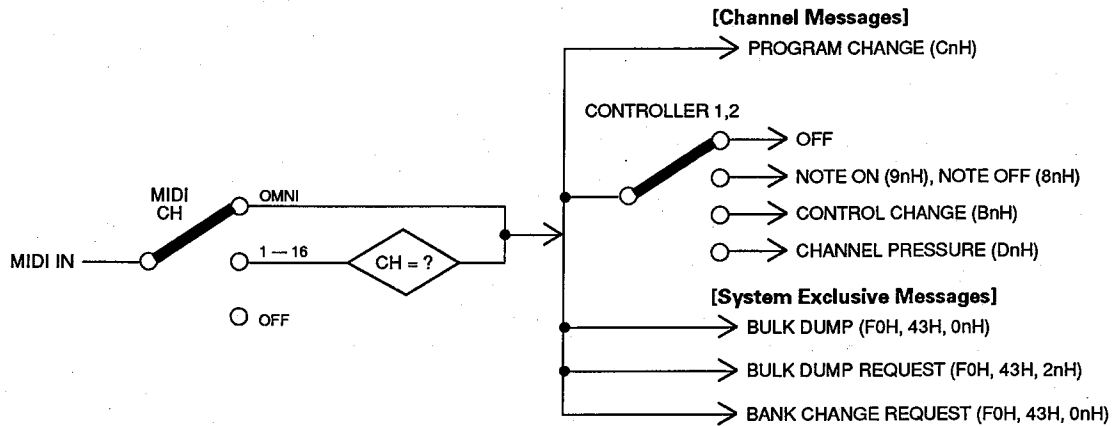
STATUS	11110000 (F0H)	SYSTEM EXCLUSIVE
ID NO.	01000011 (43H)	YAMAHA
SUB STATUS	0000nnnn	nnnn = CHANNEL NO. *1
FORMAT NO.	01111110 (7EH)	UNIVERSAL BULK DUMP
BYTE COUNT	00000000 (00H)	HEADER & DATA = 20 bytes
	00010100 (14H)	
HEADER	01001100 (4CH)	"L"
	01001101 (4DH)	"M"
	00100000 (20H)	" "
	00100000 (20H)	" "
	00111000 (38H)	"8"
	00110111 (37H)	"7"
	00110111 (37H)	"7"
	00110001 (31H)	"1"
DATA NAME	01010011 (53H)	"S" (SYSTEM SETUP DATA)
	00100000 (20H)	" "
VERSION NO.	0vvvvvvv	VERSION NO. MSB
	0vvvvvvv	VERSION NO. LSB
CHANNEL NO.	000nnnnn	bank A *13
	000nnnnn	bank B
	000nnnnn	bank C
	000nnnnn	bank D
BANK NO.	000000bb	CURRENTLY SELECTED BANK NO. *11
CONTROL NO.	0ccccccc	CONTROLLER 1 *14
	0ccccccc	CONTROLLER 2
FOOTSWITCH	0000dddd	FOOTSWITCH ASSIGNMENT *15
CHECKSUM	0eeeeeee	*10
EOX	11110111 (F7H)	

4) ALL BULK DATA

When an ALL BULK OUT operation is performed or when an ALL BULK DUMP REQUEST message is received by the EMP700, the data is transmitted on the MIDI channel specified for the currently selected BANK.

All user program data from U01 to U50, all bank program change tables A through D, and system setup data will be transmitted in this order and in the formats described in (1) to (3) above.

3. RECEPTION CONDITIONS



4. RECEPTION DATA

4-1. Channel Information

[1] Channel Voice Messages

1) NOTE ON

Received on the channel specified for the selected bank when a program with controllers 1 and 2 assigned to KEY NOTE or KEY VEL. is active or when a pitch change meter effect (TPI, SPI, P+R, P→R) and a parameter setting other than OFF are selected.

When a message is received, the value of the assigned effect parameter is changed according to the note number or velocity value or the pitch change course value changes according to the note number.

STATUS	1001nnnn (9nH)	nnnn = Channel No. *1
1st data	0kkkkkkk	kkkkkkk = Note No. *2
2nd data	0vvvvvvv	vvvvvvv = Velocity *3

2) NOTE OFF

This message affects the EMP700 only when the equipment signalling the end of a NOTE ON message is connected.

STATUS	1000nnnn (8nH)	nnnn = Channel No. *1
1st data	0kkkkkkk	kkkkkkk = Note No. *2
2nd data	0vvvvvvv	vvvvvvv = Velocity *3

3) CONTROL CHANGE

Received on the channel specified for the selected bank when a program with controllers 1 and 2 assigned to either 01 (MOD. WHEEL) ~ 31 or 64 (SUSTAIN) ~ 95 is active.

When a message is received, the value of the assigned effect parameter is changed according to the control value.

STATUS	1011nnnn (BnH)	nnnn = Channel No. *1
1st data	0ccccccc	ccccccc = Control No. *4
2nd data	0vvvvvvv	vvvvvvv = Control Value *5

4) PROGRAM CHANGE

Received on the MIDI channel specified for the currently selected bank.

When a message is received, the corresponding program is called from the program change table of the selected bank.

STATUS	1100nnnn (CnH)	nnnn = Channel No. *1
1st data	0ppppppp	ppppppp = Program No. *6

5) CHANNEL PRESSURE

Received on the channel specified for the selected bank when a program with controllers 1 and 2 assigned to CH PRES. in the UTILITY mode is active.

When a message is received, the value of the assigned parameter is changed according to the pressure value.

STATUS	1101nnnn (DnH)	nnnn = Channel No. *1
1st data	0vvvvvvv	vvvvvvv = Pressure Value *7

4-2. System Information

[1] System Exclusive Messages

1) 1 MEMORY BULK DATA

Received on the MIDI channel specified for the currently selected bank.

When received, the currently active program data is erased and replaced by the received data.

The data format is the same as for transmission.

2) 1 BANK PROGRAM CHANGE TABLE BULK DATA

Received on the MIDI channel specified for the currently selected bank.

When received, the currently active program change table is erased and replaced by the received data.

The data format is the same as for transmission.

3) SYSTEM SETUP BULK DATA

Received on the MIDI channel specified for the currently selected bank.

When received, the currently active system setup data is erased and replaced by the received data.

The data format is the same as for transmission.

4) ALL BULK DATA

Received on the MIDI channel specified for the currently selected bank.

When received, virtually all currently active data is erased and replaced by the received data.

The data format is the same as for transmission.

5) 1 MEMORY BULK DUMP REQUEST

Received on the MIDI channel specified for the currently selected bank.

When received, the data corresponding to the specified USER program is transmitted.

STATUS	11110000 (F0H)	SYSTEM EXCLUSIVE
ID NO.	01000011 (43H)	YAMAHA
SUB STATUS	0010nnnn	nnnn = CHANNEL NO. *1
FORMAT NO.	01111110 (7EH)	UNIVERSAL BULK DUMP
BYTE COUNT	00000010 (02H)	HEADER & DATA = 266 bytes
	00001010 (0AH)	
HEADER	01001100 (4CH)	"L"
	01001101 (4DH)	"M"
	00100000 (20H)	" "
	00100000 (20H)	" "
	00111000 (38H)	"8"
	00110111 (37H)	"7"
	00110111 (37H)	"7"
	00110001 (31H)	"1"
DATA NAME	01001101 (4DH)	"M" (1 MEMORY DATA)
DATA	0nnnnnnnnnn	nnnnnnnnnn = USER'S MEMORY NO. *8
EOX	11110111 (F7H)	

6) 1 BANK PROGRAM CHANGE TABLE BULK DUMP REQUEST

Received on the MIDI channel specified for the currently selected bank.

When received, the data corresponding to the program change table of the specified bank is transmitted.

STATUS	11110000 (F0H)	SYSTEM EXCLUSIVE
ID NO.	01000011 (43H)	YAMAHA
SUB STATUS	0010nnnn	nnnn = CHANNEL NO. *1
FORMAT NO.	01111110 (7EH)	UNIVERSAL BULK DUMP
BYTE COUNT	00000010 (02H)	HEADER & DATA = 266 bytes
	00001010 (0AH)	
HEADER	01001100 (4CH)	"L"
	01001101 (4DH)	"M"
	00100000 (20H)	" "
	00100000 (20H)	" "
	00111000 (38H)	"8"
	00110111 (37H)	"7"
	00110111 (37H)	"7"
	00110001 (31H)	"1"
DATA NAME	01010100 (54H)	"T" (1BANK DATA)
BANK NO.	00000bbb	bbb = BANK NO. *11
EOX	11110111 (F7H)	

7) BANK CHANGE REQUEST

Received on the MIDI channel specified for the currently selected bank.

When received, the specified bank is called up.

STATUS	11110000 (F0H)	SYSTEM EXCLUSIVE
ID NO.	01000011 (43H)	YAMAHA
SUB STATUS	0000nnnn	nnnn = CHANNEL NO. *1
FORMAT NO.	01111100 (7CH)	CONDITION SETSETUP
BYTE COUNT	00000000 (00H)	HEADER & DATA = 13 bytes
	00001101 (0DH)	
HEADER	01001100 (4CH)	"L"
	01001101 (4DH)	"M"
	00100000 (20H)	" "
	00100000 (20H)	" "
	00111000 (38H)	"8"
	00110111 (37H)	"7"
	00110111 (37H)	"7"
	00110001 (31H)	"1"
DATA NAME	01010101 (55H)	"U" (BANK CHANGE)
	00100000 (20H)	" "
VERSION NO.	0vvvvvvv	VERSION NO. MSB
	0vvvvvvv	VERSION NO. LSB
DATA	00000bbb	bbb = BANK NO. *11
CHECKSUM	0eeeeeee	*10
EOX	11110111 (F7H)	

8) SYSTEM SETUP BULK DUMP REQUEST

Received on the MIDI channel specified for the currently selected bank.

When received, the system setup data is transmitted.

```

STATUS      11110000 (F0H)  SYSTEM EXCLUSIVE
ID NO.      01000011 (43H)  YAMAHA
SUB STATUS  0010nnnn        nnnn = CHANNEL NO. *1
FORMAT NO.  01111110 (7EH)  UNIVERSAL BULK DUMP
HEADER      01001100 (4CH)  "L"
              01001101 (4DH)  "M"
              00100000 (20H)  " "
              00100000 (20H)  " "
              00111000 (38H)  "8"
              00110111 (37H)  "7"
              00110111 (37H)  "7"
              00110001 (31H)  "1"
DATA NAME   01010011 (53H)  "S" (SYSTEM SETUP DATA)
              00100000 (20H)  " "
EOX         11110111 (F7H)

```

5. NOTES

- *1 nnnn = 0 (Channel 1) ~ 15 (Channel 16)
- *2 kkkkkk = 0 ~ 127
- *3 vvvvvvv = 0 (Note OFF), 1 ~ 127
- *4 ccccccc = 1 ~ 31, 64 ~ 95
- *5 vvvvvvv = 0 ~ 127
- *6 ppppppp = 0 (Program 1) ~ 127 (Program 128)
- *7 vvvvvvv = 0 ~ 127
- *8 mmmmmmm = 0 (U01) ~ 49 (U50)
- *9 Depending on memory contents
- *10 eeeeeee is the 2's complement of the lowest 7 bits of the sum of all header and data bytes.
- *11 bbb = 1 (Bank A) ~ 4 (Bank D)
- *12 Two bytes as a set expressing a PRESET, USER, or CARD memory No.

nnnnnnnnnnnn	MEMORY NO.
0	P00
:	:
90	P90
91	U01
:	:
140	U50
141	C01
:	:
190	C50

*13 Reception channel No. of Banks A ~ D

nnnnn	CHANNEL NO.
0	OMNI ON
1	1
:	:
16	16
17	OFF

*14 Control source of Controllers 1, 2

ddddddd	CONTROL SOURCE
0	OFF
1	MOD. WHEEL
2	BREATH CONTROL
3	---
4	FOOT CONTROL
:	:
5	MIDI CTRL 5
31	MIDI CTRL 31
:	:
32	MIDI CTRL 64 SUSTAIN PEDAL
63	MIDI CTRL 95
64	MIDI NOTE ON KEY #
65	MIDI NOTE ON VELOCITY
66	MIDI CHANNEL PRESS.

*15 Foot switch assignment

dddd	SETTING
0	BYPASS
1	TAP TENPO
2	OFF

YAMAHA [Multi-Effect Processor]

Date : 11/16, 1991

Model EMP700 MIDI Implementation Chart Version : 1.0

Function ...	Transmitted	Recognized	Remarks
Basic Default Channel Changed	x x	1 - 16, off 1 - 16, off	memorised
Mode Default Messages Altered	x x *****	OMNIoff/OMNIon x x	memorised
Note Number : True voice	x *****	0 - 127 x	
Velocity Note ON Note OFF	x x	o v=0-127 x	
After Key's Touch Ch's	x x	x o	
Pitch Bender	x	x	
Control Change	1 - 31 x 64 - 95 x	o o	
Prog Change : True #	x	o	*1
System Exclusive	o	o	Bulk Dump
System : Song Pos : Song Sel Common : Tune	x x x	x x x	
System :Clock Real Time :Commands	x x	x x	
Aux :Local ON/OFF :All Notes OFF Mes- :Active Sense sages:Reset	x x x x	x x o x	
Notes: *1 = For program 1 - 128, memory P00-P90, U01-U50 C01-C50 is selected.			

MULTI-EFFECT PROCESSOR

EMP700

PARTS LIST

EMP700

■CONTENTS (目次)

ELECTRICAL PARTS(電気部品).....	1
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Notes DESTINATION ABBREVIATIONS

A : Australian model	J : Japanese model
B : British model	M : South African model
C : Canadian model	Q : South-east Asia model
D : German model	U : U.S.A. model
E : European model	V : General export model (110V)
F : French model	W : General export model (220V)
G : Belgian model	X : General export model
H : North European model	Y : Export model
I : Indonesian model	

ELECTRICAL PARTS (電気部品)

Ref. No.	Part No.	Description	部 品 名	Remarks	ランク
	VL379000	Circuit Board	AD	J,U,C,V EMP700	
	VL379100	Circuit Board	AD	H,B	
	IG001390	IC	RC4558D-V	OP AMP.	03
	XC349A00	IC	μ PC78L05J	5V REGULATOR	
	IG130500	IC	NJM79L05A	-5V REGULATOR	03
	XC719A00	IC	NJM7805FA	5V REGULATOR	02
	XC720A00	IC	NJM7812FA	12V REGULATOR	02
	XC721A00	IC	NJM7912FA	-12V REGULATOR	
	XD066A00	IC	NJM78L12A	12V REGULATOR	
	XH970A00	IC	M62021L	RESET	04
	IG147300	IC	HD63B50P	CPU/周辺IC	09
	XD245A00	IC	HD63B03YP-N	CPU/周辺IC	08
	XG517A00	IC	LC3664RL-12	メモリIC	08
	XK356A00	IC		書込済EPROM	
	XE788A00	IC	YM6104	LSI	11
	XG278A00	IC	PCM66P	IC	08
	XI112A00	IC	AK5339-VP	IC	15
	XT816A00	IC	YSS208	LSI	13
	XJ875A00	IC	YSS218-F	LSI	
	IR024500	IC	TC74HC245AP	ロジックIC	07
	IR000000	IC	TC74HC00AP	ロジックIC	03
	IR000050	IC	SN74HC00N	ロジックIC	03
	XC628A00	IC	TC51832PL-10	メモリIC	09
	XH116A00	IC	HM65256BLP-10	メモリIC	09
	VD473200	Photo Coupler	6N137	フォトカプラ	05
	IA101510	Transistor	2SA1015 Y	トランジスタ	01
	IC121340	Transistor	2SC1213A D	トランジスタ	01
	IC181510	Transistor	2SC1815 Y	トランジスタ	01
	VC710400	Transistor	2SC2878 B	トランジスタ	
	IG138700	Transistor Array	TD62506P	トランジスタアレイ	03
	VB481900	Diode	11ES4	ダイオード	01
	VB941200	Diode	1SS133, 1SS176	ダイオード	01
	IH000870	Diode Stack	4D4B41 4A 200V	ダイオードスタック	04
	IH001120	Diode Stack	S2VB20 2A 200V	ダイオードスタック	03
	VJ734900	LED	GL8KG26 GR	LED	5pcs
	VK018900	LED	GL8HD26 RE	LED	01
	VA026000	LED Display	LN524RKS	LEDディスプレイ	05
	VF771900	Resistor Array	RGLE8X103J	抵抗アレイ	01
	VF773500	Resistor Array	RGLE4X103J	抵抗アレイ	01
	VL962700	Variable Resistor	A10KX2 RK124222	ロータリーボリューム	INPUT LEVEL L,R
	UJ739220	Electrolytic Cap.	2200 μ F 16V	ケミコン	02
	UJ749220	Electrolytic Cap.	2200 μ F 25V	ケミコン	03
	FI383220	Ceramic Cap.	2200pF 400V	規格認定コン	01
	FR203100	Ceramic Cap.	0.1 μ F	規格認定コン	03
	FI383470	Ceramic Cap.	4700pF 400V	規格認定コン	01
	VC694800	Semiconductive Cera. Cap.	0.1 μ F 25V Z	半導体セラコン	01
	VB835000	Coil	FL5R200QNT	コイル	20 μ H
	GD900760	Coil	PLA3021A 3mm	コイル	06
	VH408900	LC Filter	LPF 20KHZ	LCフィルター	05
	FZ006970	EMI Filter	LS-MT V223NB	LCフィルターEMI	02
	GR300610	Ferrite Bead	BL02RN1-R62T4	フェライトビーズ	01
	QU004800	Ceramic Resonator	4MHZ CSA4.00MG	セラミック振動子	03
	VH409300	Ceramic Resonator	CSA22.5792MG	セラミック振動子	02
	VN140900	Thermistor	ERT-D2FK103S1K	サーミスタ	
	VJ557300	Push Switch	ESB-82TYPE	プッシュスイッチ	POWER
	VH475900	Slide Switch	SSSU142-S06S-0	スライドスイッチ	-20dB, +4dB
	VH476100	Slide Switch	SSSU112-S06S-0	スライドスイッチ	MIDI OUT, THRU
	VK519000	DIN Jack	5P3 YKF51-50	DINジャック2連	MIDI IN, OUT/THR
	VB312600	Phone Jack	YKB21-5012	ホーンジャック(黒)	IN, OUT, BYPASS
	-- <	IC Socket	DICF-32CS-E	ICソケット	(VJ532800)
	--	Socket	IMSA-9110S-14L	ソケット	(VM657000)
	--	Socket	IMSA-9110S-10L	ソケット	(VM686600)
	--	Socket	IMSA-9110S-05L	ソケット	(VM686700)
	VF821100	Connector, Card	IC3A38PS-1.27D	ICカード用コネクタ	MEMORY CARD 38P
	VE338400	Lithium Battery	SONY/CR2032	リチウム電池	03
	VA855400	Terminal		PC用カラゲ端子	01
	--	Angle Bracket, Jack		ジャック金具	(VL820500)
	--	Heat Sink		放熱板	(VL820700)
	VM495200	Spacer, LED		LEDスペーサー	1pc.
	--	Connector Assembly	6P 80L	束線 88	(VM702800)
	VC569900	Bind Head Tapping Screw-B	A 3.0X8 FCM3BL	+バインドBタイト	3pcs
	VC791600	Bind Head Tapping Screw-B	A 3.0X6 FCM3BL	+バインドBタイト	4pcs
	VL842500	LCD Unit		LCDユニット	
	--	IC	NJH6420-02	LSI	
	VE464300	LED	TLR220 RE	LED	01
	--	LED Back-lit		LEDバックライト	
	--	Tact Switch	SKHUQB	タクトスイッチ	
	VC021100	Tact Switch	SKHLAC023A	タクトスイッチ	01

*New Parts (新規部品)

ランク: Japan only

[illegible]

EMP700



EMP700

Ref. No.	Part No.	Description	部 品 名	Remarks	ランク
		<Overall Assembly>	<総組立>	EMP700	
10	VL810900	Bottom Cover	ボトムカバー	J	
20	VL811000	Rear Panel	リアパネル	U,V	
20	VL811100	Rear Panel	リアパネル	C	
20	VL997100	Rear Panel	リアパネル	H,B	
20	VL811200	Rear Panel	リアパネル	6pcs	
30	VC791600	Bind Head Tapping Screw-B	A 3.0X6 FCM3BL	J,U,C,V	
40	VL812700	Isolation Sheet	絶縁シート	H,B	
50	VL379000	Circuit Board	AD		
50	VL379100	Circuit Board	AD		
55	VN303700	Card Guide	カードガイド		
56	VC569900	Bind Head Tapping Screw-B	A 3.0X8 FCM3BL	2pcs	01
60	VL820600	Sub Panel	サブパネル		
70	VC791600	Bind Head Tapping Screw-B	A 3.0X6 FCM3BL	3pcs	
80	VL842500	LCD Unit	LCDユニット		
85	VN211300	LCD Spacer	LCDスパーサー	1pc.	
85	--	LCD Spacer	LCDスパーサー	(VN21130) 1pc.	
90	CB068880	Plastic Rivet	プラスチックリベット	3pcs	01
100	VM502800	Spacer	ミニカードスパーサー	2pcs	
120	VC791600	Bind Head Tapping Screw-B	A 3.0X6 FCM3BL	5pcs	
130	VC569900	Bind Head Tapping Screw-B	A 3.0X8 FCM3BL	2pcs	01
140	VC791600	Bind Head Tapping Screw-B	A 3.0X6 FCM3BL	1pc.	
145	EG330410	Bind Head Screw	A 3.0X6 FCM3BL	2pcs	01
150	VC791600	Bind Head Tapping Screw-B	A 3.0X6 FCM3BL	2pcs	
160	VC364900	Hexagonal Nut	φ9.0 FCM3BL	特殊六角ナット	01
170	XJ769B00	Power Transformer	電源トランス	J	
170	XJ771B00	Power Transformer	電源トランス	U,C,V	
170	XJ772B00	Power Transformer	電源トランス	H,B	
180	VC569900	Bind Head Tapping Screw-B	3.0X8 FCM3BL	2pcs	01
190	MG002290	AC Cord	7A 125V 2m	電源コード	03
190	VD654200	AC Cord	10A 2.44m	電源コード	05
190	VD279600	AC Cord	10A 2.5m	電源コード	08
190	VD279800	AC Cord	6A 2.5m	電源コード	08
190	VH890200	AC Cord	10A 2.5m	電源コード	09
200	CB068630	Cord Strain Relief	SR-3P-4	コードストッパー	01
200	VD705000	Cord Strain Relief	SR-5KN-4	コードストッパー	02
200	CB806850	Cord Strain Relief	SR-6N3-4	コードストッパー	02
200	CB032840	Cord Strain Relief	SR-5N-4	コードストッパー	01
210	LA003690	Lug Terminal	ラグ端子	U,C,H,B,V	01
220	EP600780	Bind Head Tapping Screw-B	4.0X8 FCM3BL	U,C,H,B,V(1pc.)	01
230	VL810700	Front Assembly	フロント Ass'y		
230a	VL813000	Escutcheon, Power Switch	P S W エスカッション		
240	VC791600	Bind Head Tapping Screw-B	A 3.0X6 FCM3BL	6pcs	
250	VL821700	Knob, Volume	VRツマミ(内)	INPUT LEVEL/L	
260	VL821800	Knob, Volume	VRツマミ(外)	INPUT LEVEL/R	
270	VL812900	Knob, Power Switch	P S W ツマミ	POWER	
280	VL811300	Top Cover	トップカバー		
285	VM919400	Isolation Sheet-S	絶縁シート(S)		
290	VC791600	Bind Head Tapping Screw-B	A 3.0X6 FCM3BL	8pcs	
300	CB037120	Foot	スベリ座	4pcs	01

